High reliability
Glass composite Circuit board materials

Applications
Automotive component, Power supply board, Power device module board, Infrastructure(Smart meter, IC tag), etc.

Improved solder joint reliability compared with conventional CEM-3 which has already good to safety and long-time reliability property. Contribute to high reliability PCB for electric car.

Circuit Board Materials
電子回路基板材料

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General properties
一般特性

<table>
<thead>
<tr>
<th>Item</th>
<th>Test method</th>
<th>Condition</th>
<th>Unit</th>
<th>R-1785</th>
<th>Our conventional CEM-3</th>
<th>Our conventional FR-4</th>
</tr>
</thead>
<tbody>
<tr>
<td>Glass transition temp.(Tg)</td>
<td>TMA</td>
<td>Temp. rising rate: 10℃/min</td>
<td>℃</td>
<td>150</td>
<td>140</td>
<td>140</td>
</tr>
<tr>
<td>CTE x-axis</td>
<td>α1 IPC-TM-650 2.4.41</td>
<td>TMA</td>
<td>ppm/℃</td>
<td>19 (15)</td>
<td>25 (20)</td>
<td>13</td>
</tr>
<tr>
<td>CTE y-axis</td>
<td>α1 IPC-TM-650 2.4.24</td>
<td>TMA</td>
<td>ppm/℃</td>
<td>21 (17)</td>
<td>28 (23)</td>
<td>15</td>
</tr>
<tr>
<td>Tracking resistance</td>
<td>IEC 60112</td>
<td>A</td>
<td>V</td>
<td>-</td>
<td>CTI≥600</td>
<td>CTI≥600</td>
</tr>
<tr>
<td>Accuracy of thickness(σ value)</td>
<td>A</td>
<td>A</td>
<td>mm</td>
<td>0.013</td>
<td>0.013</td>
<td>0.027</td>
</tr>
</tbody>
</table>

The above data is actual values and not guaranteed values. 上記データは当社の実測値であり、保証値ではありません。
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